

# 2016 NETL Crosscutting Research Review Meeting

April 18-22, 2016

SBIR Phase IIA Project: DOE 12-14C

Contract #: DE-SC-0008269

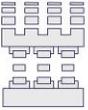
## Advanced Ceramic Materials and Packaging Technologies for Realizing Sensors Operable up to 1800 Celsius in Advanced Energy Generation Systems

Authors: Yiping Liu (PI), Jason Fish (**Presenter**), Laurel Frediani, Michael Usrey

Contact: Jason Fish, Email: [jfish@sporian.com](mailto:jfish@sporian.com),

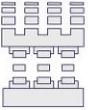
Phone Number: 303-516-9075 x**31**

**Sporian Microsystems, Inc.** ([www.sporian.com](http://www.sporian.com))  
515 Courtney Way - Suite B, Lafayette, CO 80026-8821



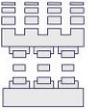
# Acknowledgement

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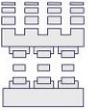
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# Overview

- Sporian Introduction
- Project Motivation
- Prior, Related Work
- Current Effort Progress Update



# About Sporian Microsystems

- Sporian develops advanced sensors and sensor systems for a range of applications.

## Core Technical Competencies

Novel Materials Science

Leading edge signal Conditioning & Smart Electronics

Advanced Electronics & Hardware Packaging

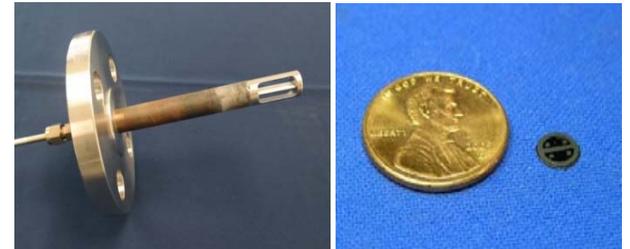
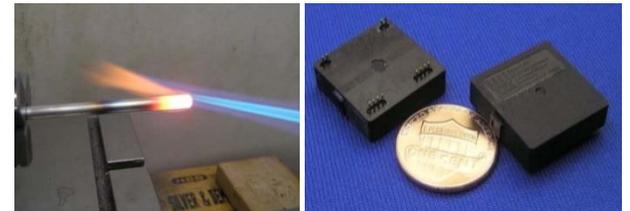
## Advanced Sensor Technologies

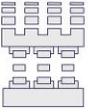
### Biological & Chemical

- Water Quality
- Gas Composition
- Biomedical
- Hyperspectral Imaging

### Energy & Aerospace

- Very High Temperature
- Harsh Environments
- Asset monitoring
- PHM



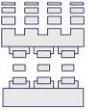


# Overview of Sporian's Harsh Environment/High Temperature MEMS Sensors and Packaging

R&D focus area on **high-temperature sensors** and **packaging**

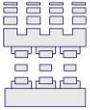
- Directly monitor the most harsh/costly sections of equipment
  - Pressure, temperature, flow, flame ionization, strain, etc.
  - Packaging a critical enabler
- Started with **DOE-funded basic science SBIR 2003**
- Aerospace (turbine engines)
  - Air Force, Navy, NASA funded
- Energy generation (gas turbines, coal gasification, nuclear, CSP, etc.)
  - **DOE funded**
- Prior work predominantly focused on  $<1400\text{ }^{\circ}\text{C}$  application
- **Current DOE project focusing on extending capabilities to  $1800\text{ }^{\circ}\text{C}$**





# Motivation

- Higher turbine efficiencies achievable at higher combustion temperatures ( $\leq 1800$  °C depending on fuel).
- Existing thermocouples (TCs) for combustor monitoring are **expensive** and **short-lived**
  - Practical only in design phase of turbine life-cycle.
- TCs used at turbine exhaust (lower temp) to infer combustor temperature -- **limits efficiency**
- Additional efficiency gains possible with dynamic pressure measurement.



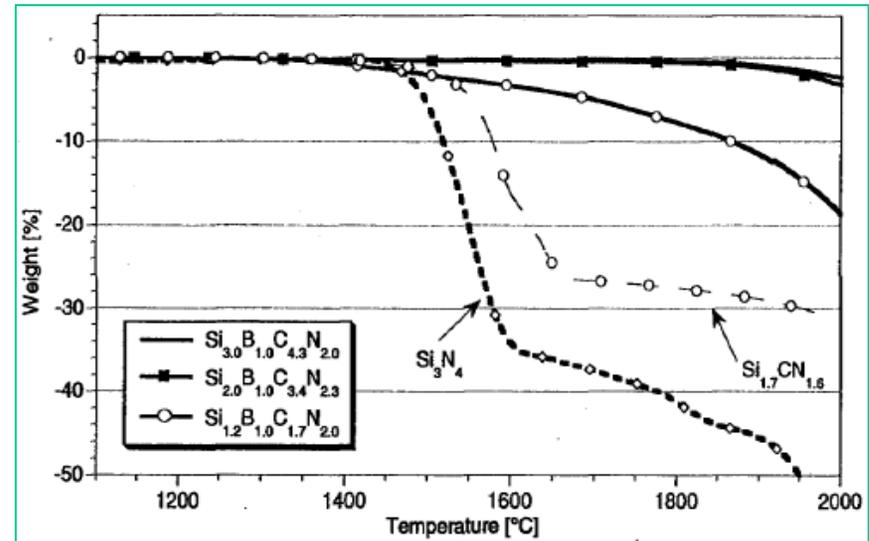
# Ultra-High Temperature SiCN Ceramics

- SiCN has shown excellent HT thermo-mechanical properties.
- Sporian existing polymer-derived ceramic (**PDC**) SiCN formulations can work safely under 1350 °C
- SiBCN is thermally stable up to 1800 °C

## Selected Literature Review of SiBCN

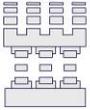
Empirical Formula	Maximum Stable Temperature	Selected Reference from More than 100 Papers/Reviews
$\text{Si}_{2.9}\text{B}_{1.0}\text{C}_{14.0}\text{N}_{2.9}$ $\text{Si}_{5.3}\text{B}_{1.0}\text{C}_{19.0}\text{N}_{3.4}$	2200°C-30min	Wang and Riedel, 2001
$\text{Si}_{3.0}\text{B}_{1.0}\text{C}_{4.3}\text{N}_{2.0}$	~2000°C	Riedel, 1996
$\text{Si}_{1.0}\text{B}_{1.0}\text{C}_{1.6}\text{N}_{2.4}$	~1785°C	Wilfert and Jansen, 2012
$\text{Si}_{1.0}\text{B}_{1.0}\text{C}_{1.7}\text{N}_{2.3}$	~1700°C	Weinmann, 2008
$\text{Si}_{2.0}\text{B}_{1.0}\text{C}_{3.4}\text{N}_{2.3}$	~1600°C	Zhang, 2011
$\text{Si}_{1.0}\text{B}_{1.0}\text{C}_{2.0}\text{N}_{2.8}$	>1400°C	Tang, 2009

## Weight Loss at High Temperatures (in UHP He)



## Challenges:

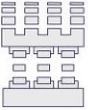
- Synthesis of new precursors
- Viscosity control for workability/patternability
- UV cure capability to make useful devices
- Optimized pyrolysis processing
- Contamination and defect control for thermal stability



# Prior, Related Work <1400 °C - PDCs

## Features, Advantages and Benefits

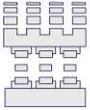
Features	Advantages	Benefits
Polymer-derived ceramic ( <b>PDC</b> ) materials	<ul style="list-style-type: none"><li>• Operating temperature &gt;1000 °C w/o liquid cooling or fiber routing</li><li>• Pressures ≥1000 psia</li><li>• High oxidation/corrosion resistance</li><li>• Thermal shock resistance</li><li>• Low creep rate &amp; diffusion rate</li></ul>	<ul style="list-style-type: none"><li>• Lower weight, smaller size</li><li>• Lower cost, low-maintenance</li><li>• Higher durability</li><li>• Higher operational availability</li></ul>
Temperature / pressure sensor suite	<ul style="list-style-type: none"><li>• Improved T-compensation of pressure measurements</li><li>• Opportunity for redundancy and/or multi-sensor package</li></ul>	<ul style="list-style-type: none"><li>• Lower weight, smaller size</li><li>• Higher accuracy</li></ul>
Immersion sensing at source	<ul style="list-style-type: none"><li>• Eliminate stand-off tubes</li><li>• Avoid tube moisture collection</li></ul>	<ul style="list-style-type: none"><li>• Lower cost, higher accuracy</li><li>• Reduced weight</li><li>• Improved dynamic response</li><li>• Reduced latency</li><li>• <b>Avoid failure mechanism</b></li></ul>
Electronics-based	<ul style="list-style-type: none"><li>• Compatible with existing controls &amp; CBM</li></ul>	<ul style="list-style-type: none"><li>• Lower cost</li></ul>



## Prior, Related Work <1400 °C Performance

<b>Specification</b>	<b>PIWG* Target</b>	<b>Achieved by Sporian</b>
Pressure Range (psi)	25-750	Atm-1000
Operation Temperature (°C)	700-1350	25-1350
Natural Frequency	>100 kHz	TBD
Internally Compensated Temp. Range (°C)	700-1350	700-1350
Length (in)	1.25-3.00	1-10 (modifiable)
Diameter (in)	<0.25	0.25
Sensitivity/Combined Uncertainties	≤ 1% FS	≤ 1% FS
Power (VDC)	5-10	12 V (modifiable)

\*Propulsion Instrumentation Working Group



# Prior, Related Work <1400 °C

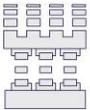
## Demonstrations (various projects)

Asset	Station	Hours *	Max T (°C)	Max P (psi)
Laboratory	N/A	-	1400	1000
Mult. OEM Burner Rigs	N/A	535	**	**
DOE Burner Rig	N/A	150	1000	30
Honeywell HTF 7000	P3	24	**	**
GE (NAVAIR) T700	P3	200	**	**
OEM Engine	P3, P4, P4.5	100	**	**

Asset	Type	Hours *	Max T (°C)	Max P (psi)
Sandia Nitrate Salt Soak	Flow/P/T	500	300	N/A
UW Chloride Salt Soak	Flow/P/T	500	750	N/A
UW Nitrate Salt Soak	Flow/P/T	500	500	N/A
Skyfuel Molten Salt Loop	Flow/P/T	80	300	50
USGS: Neutron $10^{19}$ n/cm <sup>2</sup>	various	N/A	N/A	N/A

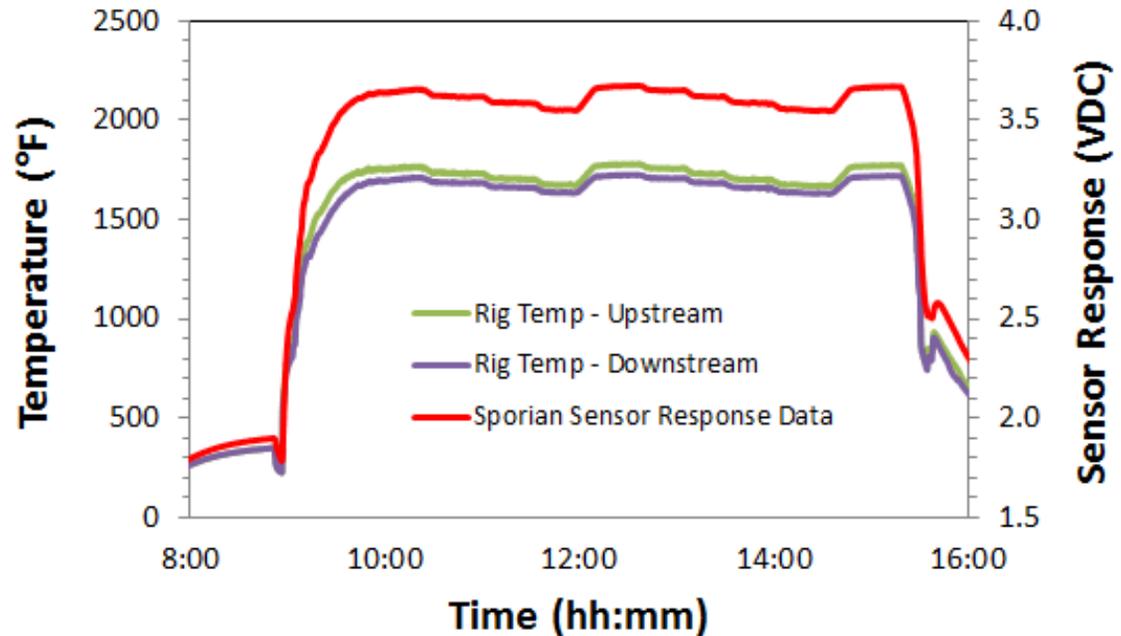
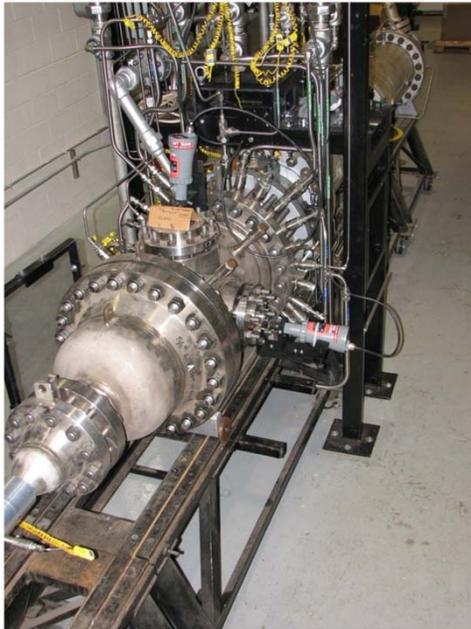
\* Test durations dictated by budgets. All sensors were fully operational after test completion.

\*\* **Proprietary**



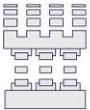
# NETL Rig Testing Results

## Aerothermal Rig

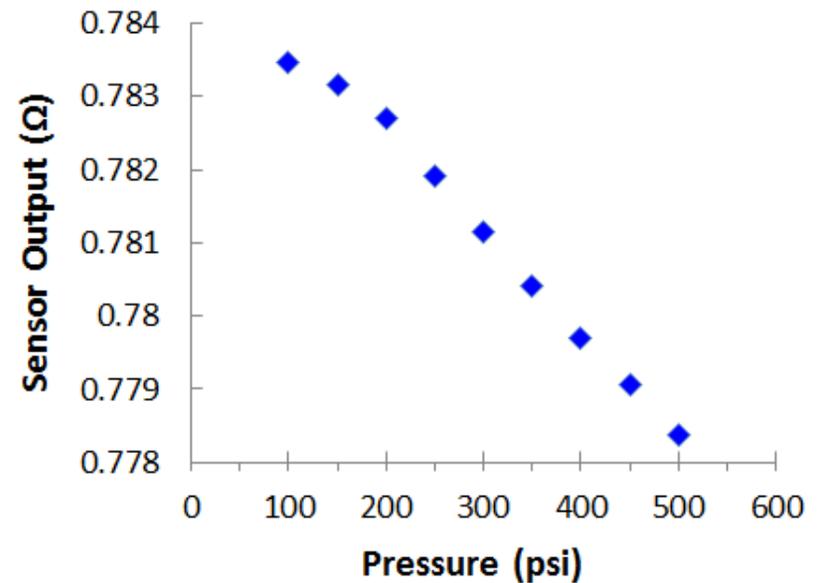
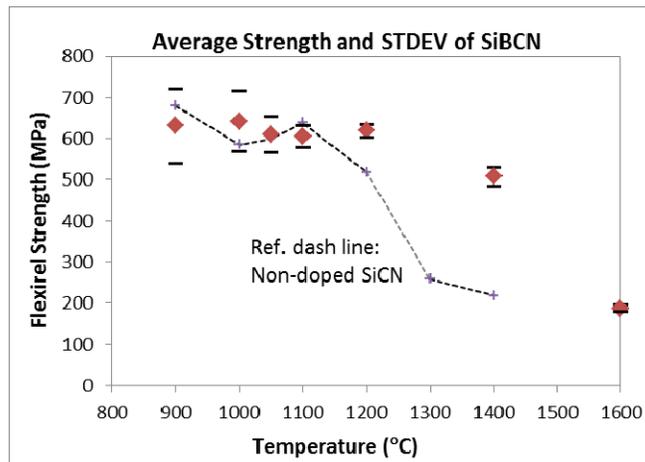
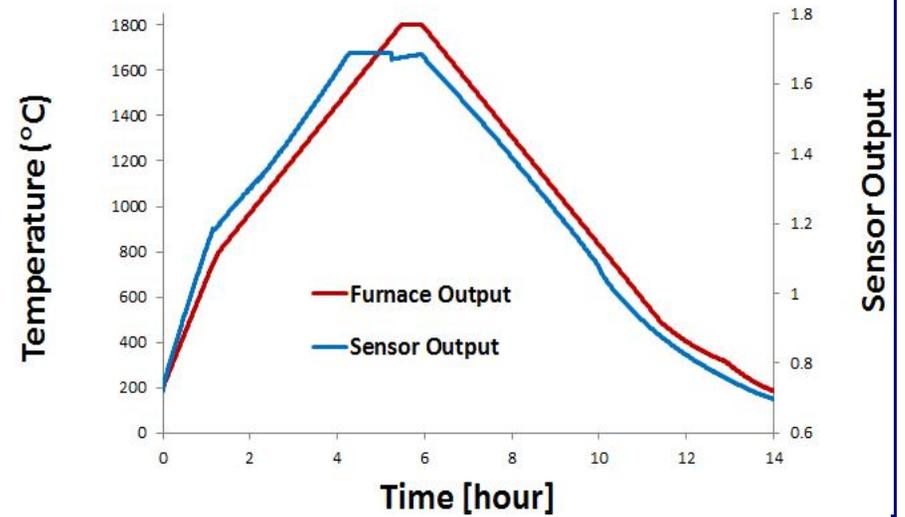
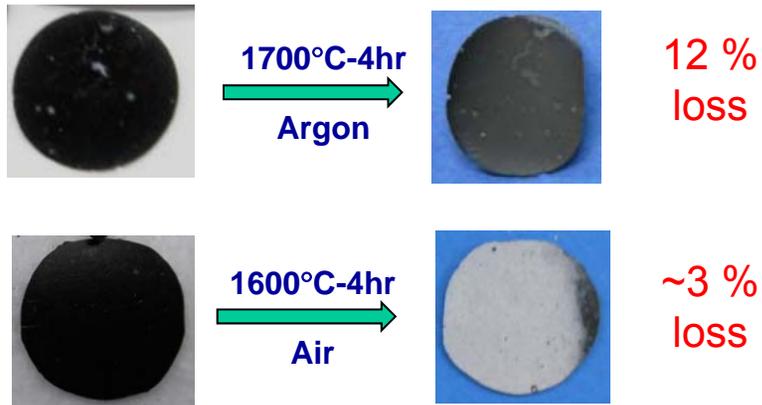


## 2014 Preliminary Results:

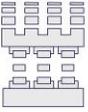
- Testing date: 10/29, 11/5, 11/12/2014
- 3x test cycles
- Maximum T : 1100 °C
- Total duration: 30 hours
- **Stable response and performance**



# Phase II In Brief



- Developed sensors and packaging capable of 1800 °C operation
- Conducted pressure response testing on 1600 °C-capable probe



# Current Effort Progress Update

- Extend Sporian's Existing Ceramic Sensors and Packaging Technology to Ultra-high Temperatures (UHT): 1600-1800°C
- Build on PII tasks for sensors, packaging, electronics to push capabilities to 1800 °C

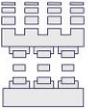
1. Work with OEMs to guide the design and development of UHT sensor technology: Commercialization and transition efforts.

2. Continue optimizing PDC precursor formulation and device fabrication to further extend capability to 1800 °C

3. Develop improved UHT P/T sensors, packaging, and drive/conditioning electronics

4. Rigorous lab-scale testing of optimized sensors/packaging to promote post Phase IIA transition, **emphasize reliability assessment**

5. Revise sensor suite designs based on test results, construct next generation prototypes, and demonstrate a full prototype sensor in stakeholder test systems



## OEM Collaboration/Coordination

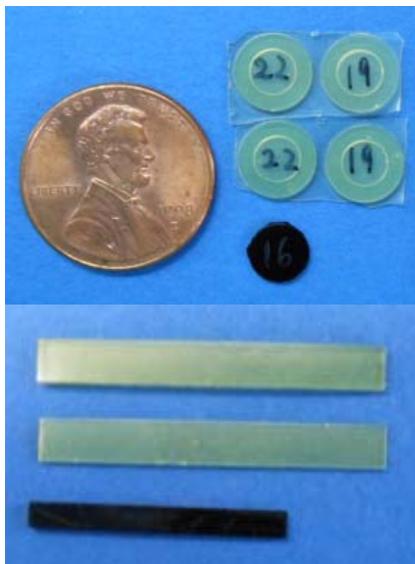
- Strong interest, requirements, and some in-kind support from:
  - Turbine OEMs
  - Controls/CBM OEMs
  - **Industry Research Institutions & Consortia**
  - Academic Institutions
  - Established sensor OEMs



# Synthesis, Evaluation of Fully Dense SiBCN

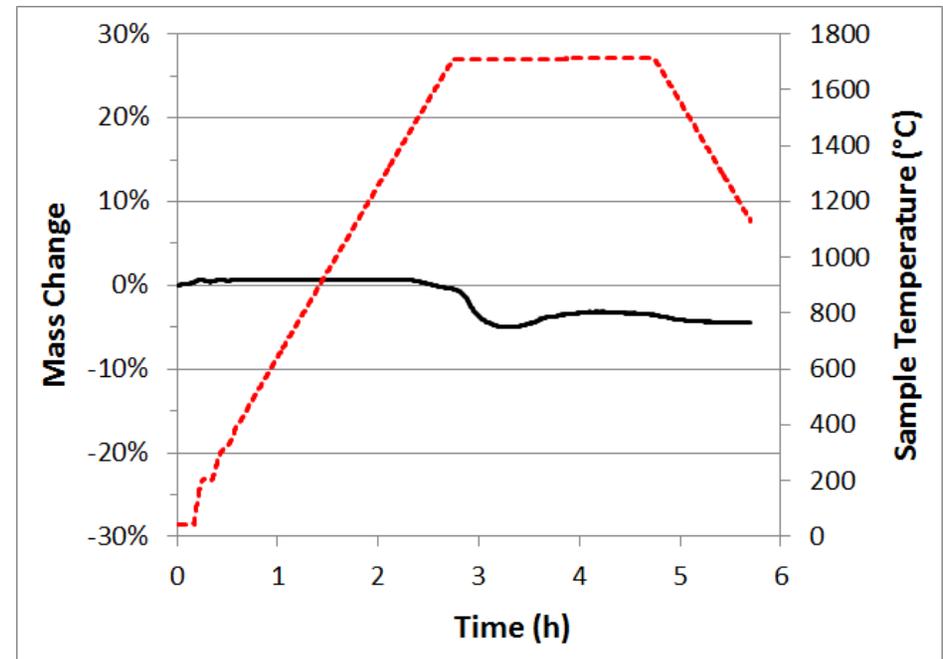
- Synthesized boron-doped polysilazane with good workability/stability
- Incorporated UV-curability to polyborosilazane precursors
- Achieved dense SiBCN ceramic materials and defect-free parts

## UV-Curable Precursor and Fired SiBCN



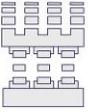
B-doped Polymer and  
SiBCN Sensor and Coupons

## Thermogravimetric Analysis of SiBCN



2 h at 1700 °C in air: ~ 5 % loss

- Sensor-ready material
- In line with best-case literature (powders)



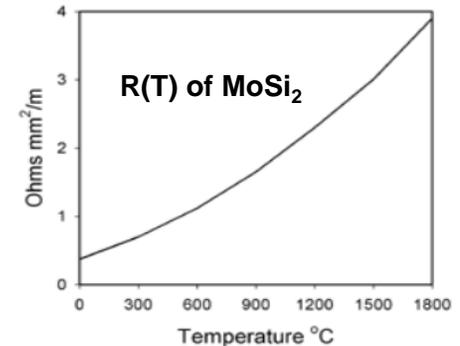
## Sporian SiBCN in Phase IIA

- B-doped composition focus – optimize precursor process, green part fabrication and handling, and fully-dense part and device processing
- Increase thermal stability in application-relevant environments
- Evaluate mechanical and chemical properties at increased temperatures
- Incorporate into sensor packaging for 1800 °C temperature and 1600 °C pressure sensor suites

# Ultra-High Temp MoSi<sub>2</sub>-based Sensors

## Sporian Sensor Materials, Prototypes:

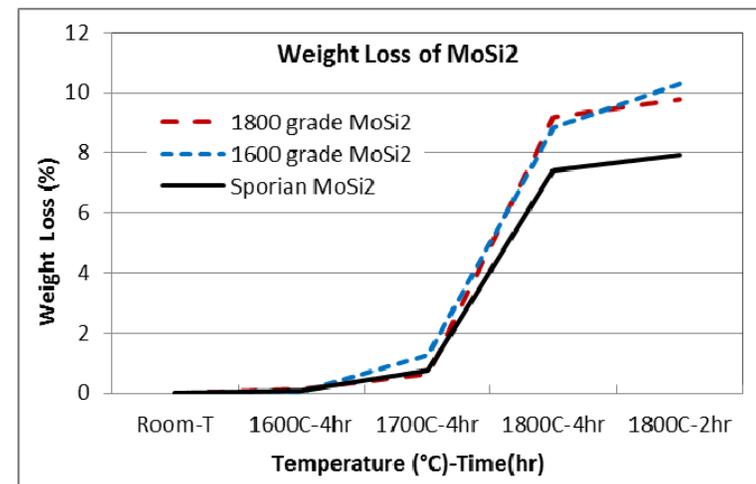
- Re-shapeable and stackable green tape, thick film inks as well
- Micro-fabrication and laser machinability
- High density (98 %) and high strength (351 MPa)
- Thermal stability and oxidation resistance at 1800 °C
- Comparable to the commercially available UHT grade (heater elements)
- Compatible CTE with alumina substrates and tapes



## Sintered Structures and Packaged MoSi<sub>2</sub> Temp Sensor Element

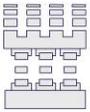


## Embedded MoSi<sub>2</sub> RTD Temp Sensor – design and results



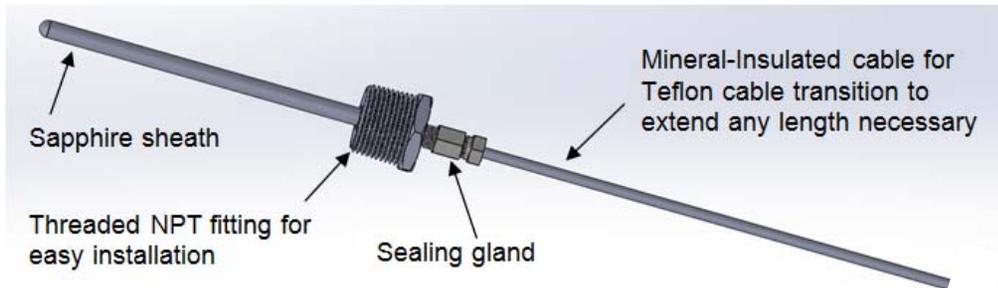
## Challenges:

- Thermal stability
- Optimizing embedding layers for sensor efficiency, accuracy
- Interconnects to sensor electronics



# Current Prototype 1800 °C Temperature Sensor (Designed for NETL Rig Testing)

## Sporian Sensor Packaging Design and Probe Assembly



**‘Smart’ Signal  
Conditioning  
Electronics**

### Features:

- Sapphire-sheathed UHT sensor packaging.
- Probe suitable for high pressures, high temperatures and particulate exposure.
- “Smart” signal conditioning electronics can drive the sensor over its entire operational range and measure the response.

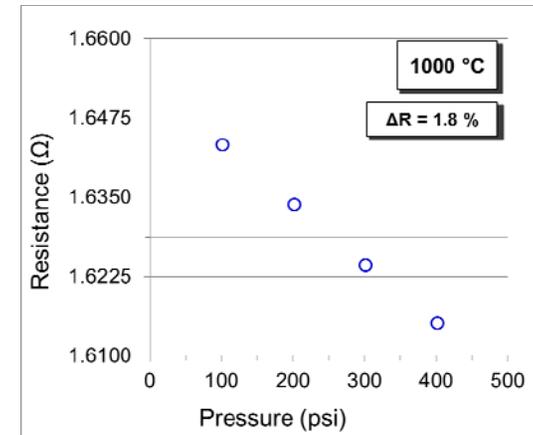
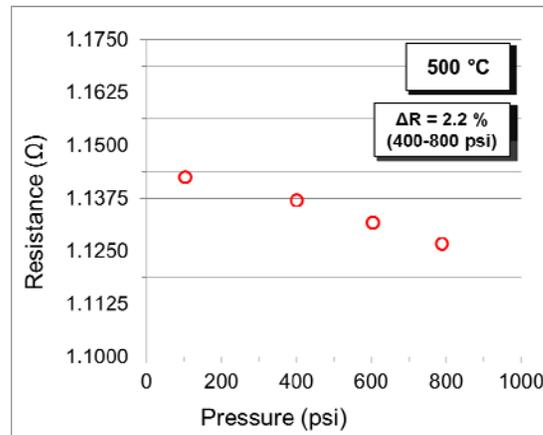
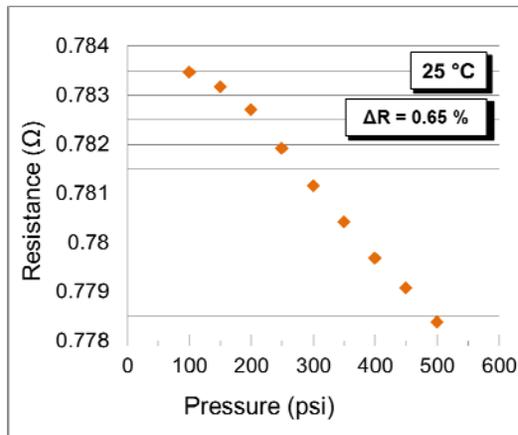
# HT Testing of Sporian Prototypes

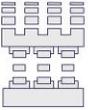


## Test under Pressure at Temp:

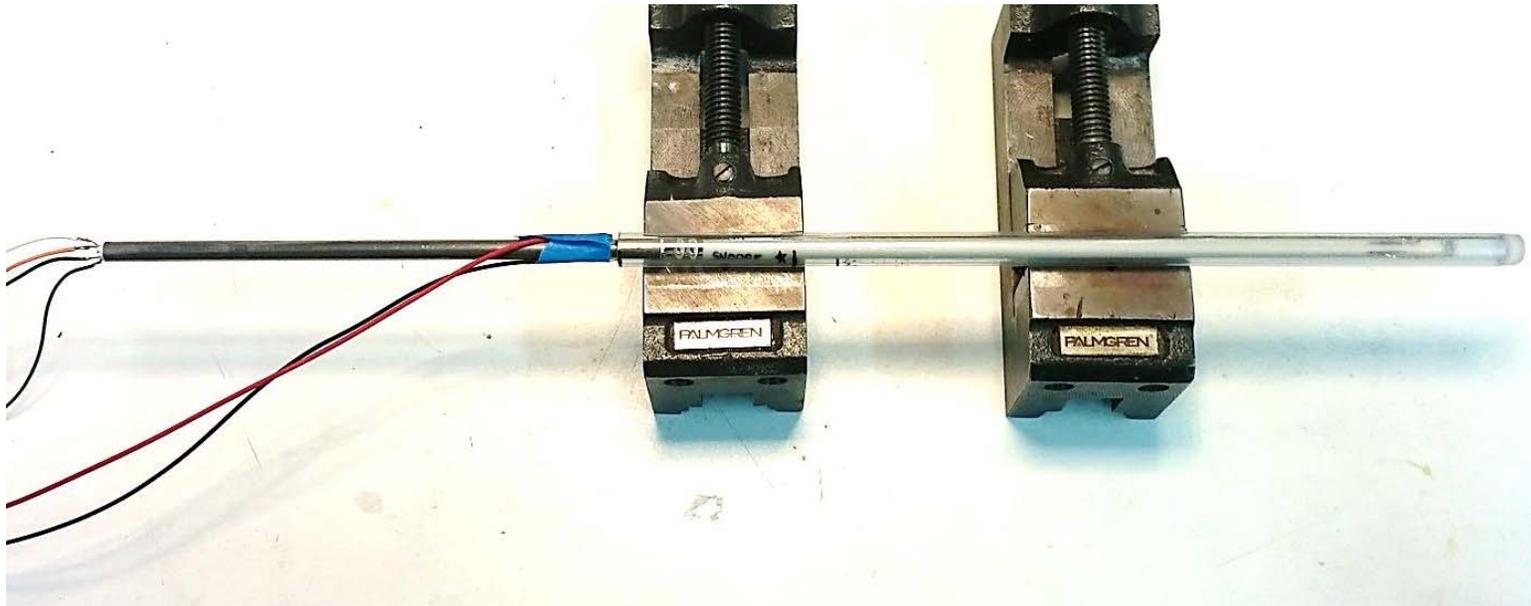
- Exterior reference TC to track temperature
- 25, 500, and 1000 °C
- 15 – 800 psi
- Sensor response increased with increasing pressure
- Sensor and package stable, no degradation

## Sporian In-House Pressure Test



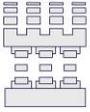


# Current HT Stability Testing (Designed for SwRI Rig)



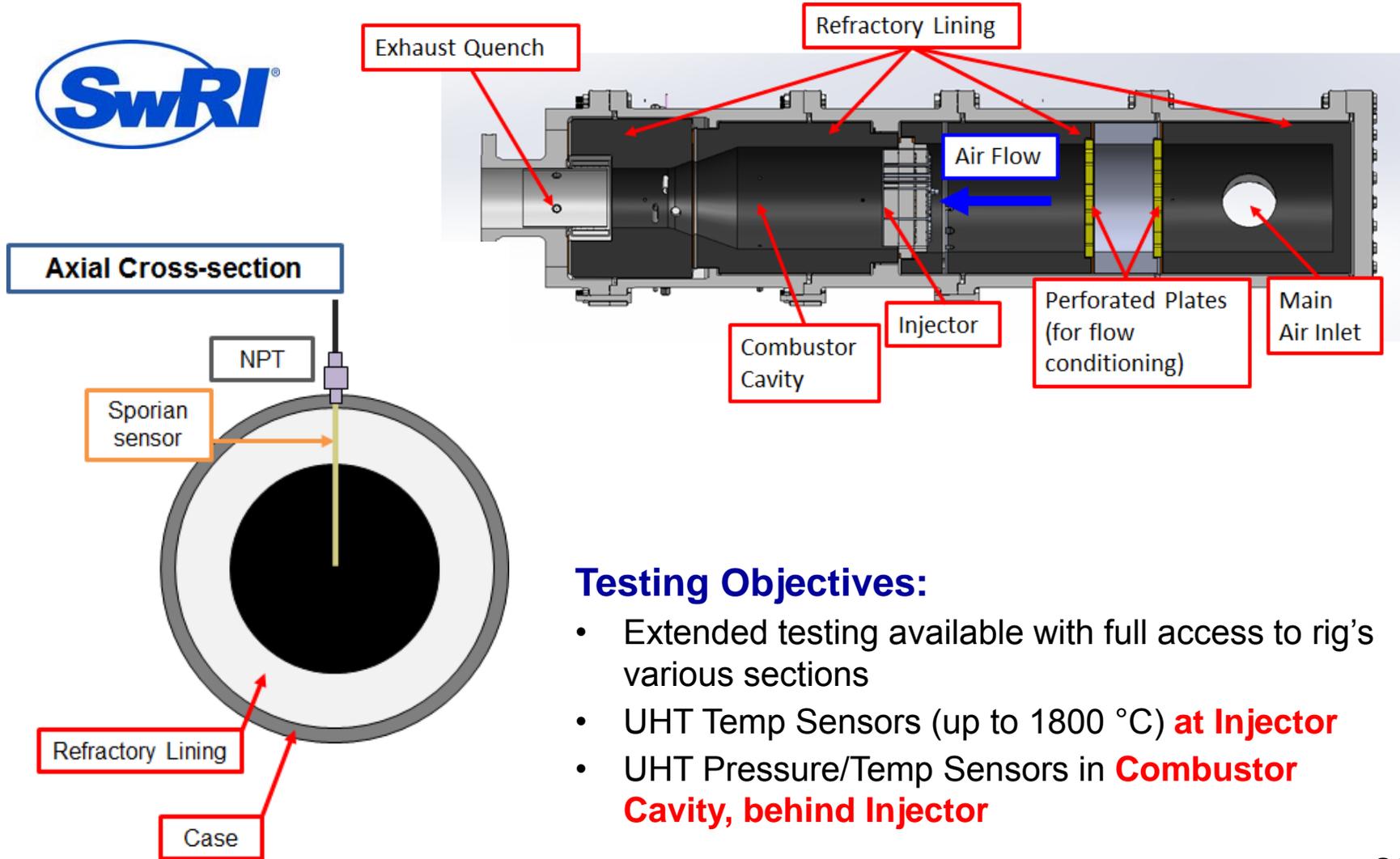
## HT Test in-house:

- Heated to **1800 °C in air**
- 1 h hold
- Element and *in-situ* TC stable post-test
- Packaging stable – no cracking, warping, or degradation



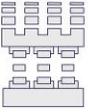
# SwRI PHTFF Rig Testing – Upcoming in PIIA

## Pressurized High-Temperature Flow Facility (PHTFF)



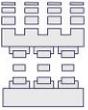
### Testing Objectives:

- Extended testing available with full access to rig's various sections
- UHT Temp Sensors (up to 1800 °C) **at Injector**
- UHT Pressure/Temp Sensors in **Combustor Cavity, behind Injector**



## Summary

1. Optimizing UV-curable/patternable PDC precursor materials and processing
2. Enhancing thermal, mechanical, and chemical stability of PDC materials and alternatives ( $\text{MoSi}_2$ ) in sensor prototypes
3. UHT packaging temperature probes survived 1800 °C in lab and 1100 °C 30 h NETL Aerothermal Rig Test
4. Preparing for extended testing in SwRI PHTFF rig to evaluate 1800 °C temp sensors and 1600 °C pressure sensors



# Thank you for your attention!

## Questions?

[www.sporian.com](http://www.sporian.com)

# NETL Aerothermal Rig Testing Results

